

THIN FILM SYSTEMS FOR RESEARCH & PRODUCTION

ATS 500. The flexible research & production thin film deposition system from HHV Ltd.

ATS 500 is designed for research and small batch production in OLED and organic electronics applications, photovoltaics, semiconductor devices, lenses and optical filters.

The system features a full-colour, touch-screen PLC with integrated process recipe control and data logging functions.

PC control is available as an option.

ATS 500 is offered with a wide range of process options including:

- Resistance evaporation sources
- Temperature controlled evaporation sources for OLED and organic photovoltaic applications
- Electron beam sources for high-rate evaporation and lift-off processes
- Ion-beam assistance for optical applications or substrate cleaning.
- DC, RF and pulsed DC for sputtering of metals and dielectrics with upward or downward sputter processes
- Combination systems featuring two or more of the above



Features and benefits

- Flexibility wide range of processes in a single system package
- Ion beam processes for optical coating applications
- Cost ATS 500 is designed as an affordable, versatile system

PROCESS FLEXIBILITY

System control

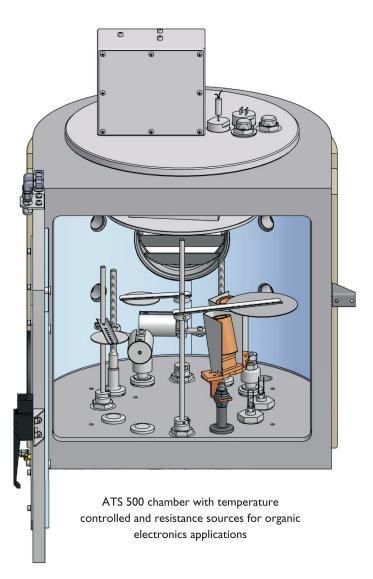
ATS 500 is fitted with a full-colour, touch-screen PLC-based HMI. The system features recipe control for single or multi-layer films plus full manual control where required. Data logging is provided along with remote support and assistance.

An optional PC-based system is provided for users requiring process report generation.

Thermal evaporation.

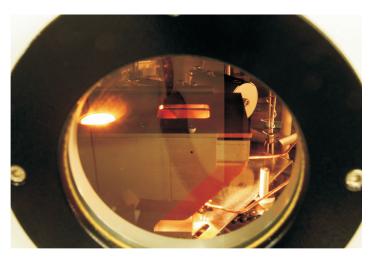
The ATS 500 chamber can be fitted with one or more thermal resistance sources. HHV's thermal sources can be adjusted to almost any position in the chamber for optimum performance.

ATS 500 also accommodates temperature-controlled, low-temperature evaporation sources for specialist research applications.



Electron beam evaporation

Options range from compact 4-pocket sources to 8kW or 12kW sources with up to 8 pockets.



Electron beam deposition in operation

Sputtering

Sputter systems are fitted with tilt and height - adjustable magnetron sputter sources with integrated shutters.

Available with 50mm, 75mm or 100mm targets these sources can be fitted singly or in multiple, or even in combination with other types of source to create a truly versatile thin film deposition system.

DC, RF or Pulsed DC operation with comprehensive source switching options for process flexibility.



ATS 500 chamber with two 100mm sputter sources & ion beam source

Mass flow control

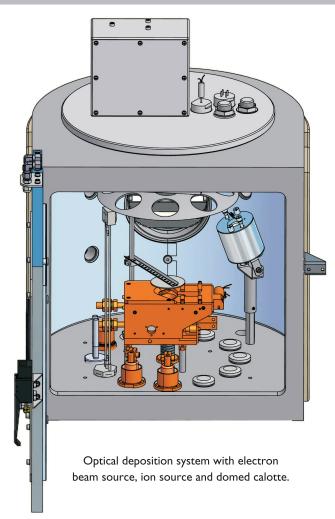
Options include:

- Single, dual or multiple gases
- Pressure control systems

COMPREHENSIVE CAPABILITIES

APPLICATION FOCUS. OPTICAL COATINGS:

By fitting a compact electron beam source and ion source, the ATS becomes a highly functional and affordable system for optical research and pilot production.



Substrate stages

ATS 500 systems can be specified with a wide range of substrate stages:

- Plane rotary with quick-release platen
- Water-cooled rotary
- Domed calotte
- Planetary
- RF or DC bias
- High temperature heating to 800C
- Z-lift for sample transfer

Sample handling

Handler options include:

- · Load lock with rotary or turbo pump
- Telescopic transfer arm
- Magnetic transfer arm
- Manual or motorised operation

Film thickness monitoring and control

Film thickness monitoring options include a two-channel rate monitor which is integrated into the touch screen. The integrated monitor includes shutter control for end point control.

Conventional film thickness monitors and film deposition controllers can also be fitted.

Chamber

The standard chamber is 500 mm (19) wide $\times 500 \text{mm}$ tall, and is constructed from stainless steel with a wide-opening aluminium front door and viewport.

Optional extended-height versions are available for applications such as lift-off. Chambers are water-cooled where high-temperature processes are specified.

Vacuum systems

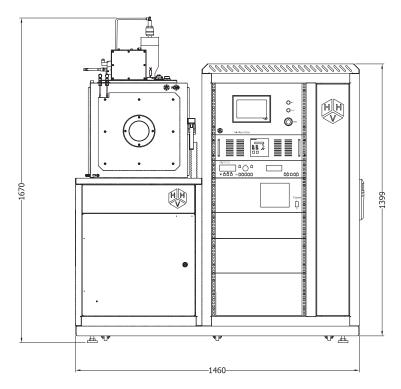
ATS 500 provides clean, high vacuum for deposition processes:

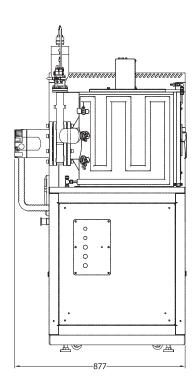
- · Conventional or mag-lev turbo pumps
- Cryo pumping
- · Rotary or dry scroll foreline pumps
- Optional gate valve (standard for cryo pump, sputter or ion processes)



Turbo pump and optional gate valve

TECHNICAL INFORMATION





ATS 500 outline dimensions (mm)

TECHNICAL DATA

ATS 500

Chamber : 500mm wide x 500mm tall. Tall options for lift-off. Stainless steel with aluminium door

: 400 l/s or 1000 l/s conventional turbo. Mag-lev options Turbo pump

: I500 l/s cryo pump Cryo pump

: Rotary pump or dry scroll pump Backing/roughing

: Atm to 1×10^{-6} mbar <40 minutes, ultimate vacuum better than 5×10^{-7} mbar (with 400 l/s turbo pump and Vacuum

clean, dry, empty 500mm chamber)

: Approx. 450kg to 500kg, specification dependant Weight

Process accessories

Mass flow control

Resistance sources : Single or multiple, IkVA or 2kVA

Organic sources : Temperature-controlled Icc, 4cc, I0cc, single or multiple sources

Electron beam sources: 3kW (4 x 4cc) or 6kW or 12kW (4 x 7cc, 6 x 7cc, 4 x 15cc, 6 x 15cc, other)

Sputter sources : 50mm (2") to 150mm (6"), fixed height, variable height, tilt

Sputter configuration : Upward or downward

Ion sources : Compact ion source options for etch or assisted deposition

: Single gas, dual gas, multiple gas. Chamber pressure control systems : Rotary, water cooled, heated (quartz lamp or resistance heated), Substrate holders

RF or DC bias, z-axis lift for sample transfer, domed calotte, planetary

: Turbo pumped with manual or motor driven transfer arms Load lock systems

: Single or multiple techniques in same chamber Combination systems



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